

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
HUNG-LI CHIANG	10/25/2019
CHIH-SHENG CHANG	12/25/2019
TZU-CHIANG CHEN	12/25/2019
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	8, LI-HSIN RD. 6
Internal Address:	HSINCHU SCIENCE PARK
City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300-78
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	18331241
CORRESPONDENCE DATA	
Fax Number:	(216)502-0601
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	2165020600
Email:	docketing@epiplaw.com
Correspondent Name:	ESCHWEILER & POTASHNIK, LLC
Address Line 1:	3500 MASSILLON ROAD
Address Line 2:	SUITE 420
Address Line 4:	UNIONTOWN, OHIO 44685
ATTORNEY DOCKET NUMBER:	TSMCP1091USB
NAME OF SUBMITTER:	JIM REUTER
SIGNATURE:	/Jim Reuter/
DATE SIGNED:	06/08/2023
Total Attachments: 5	
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PATENT ASSIGNMENT

PARTIES TO THE ASSIGNMENT

Assignor(s):

Hung-Li Chiang

Assignor(s):

Chih-Sheng Chang

Assignor(s):

Tzu-Chiang Chen

Assignee:

Taiwan Semiconductor Manufacturing Co., Ltd.
No. 8, Li-Hsin Rd. 6, Hsin-Chu Science Park
Hsin-Chu, Taiwan 300-77
Republic of China

AGREEMENT

WHEREAS, ASSIGNOR(S) (listed above) are inventor(s) of an invention entitled

"FeFET OF 3D STRUCTURE FOR CAPACITANCE MATCHING" for which:

a non-provisional application for United States Letters Patent:

☒ was executed on even date preparatory to filing (each inventor should sign this

Assignment on the same day as he/she signs the Declaration); or

☐ was filed on _____ and accorded U.S. Serial No. _____; or

☐ I hereby authorize and request my attorney associated with Customer No.

107476, to insert on the designated lines below the filing date and application

number of said application when known:

U.S. Serial No. _____

filed on _____

WHEREAS, ASSIGNEE (listed above), a corporation of the Republic of China is
desirous of acquiring the entire right, title and interest in and to the invention and in and to

any letters patent that may be granted therefore in the United States and in any and all foreign countries;

NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR(S) hereby sell, assign and transfer unto ASSIGNEE its successors and assigns, the entire right, title and interest in and to said invention and improvements, said application and any and all letters patent which may be granted for said invention in the United States of America and its territorial possessions and in any and all foreign countries, and in any and all divisions, reissues, re-examinations and continuations thereof, including the right to file foreign applications directly in the name of ASSIGNEE and to claim priority rights deriving from said United States application to which said foreign applications are entitled by virtue of international convention, treaty or otherwise, said invention, application and all letters patent on said invention to be held and enjoyed by ASSIGNEE and its successors and assigns for their use and benefit and of their successors and assigns as fully and entirely as the same would have been held and enjoyed by ASSIGNOR(S) had this assignment, transfer and sale not been made. ASSIGNOR(S) hereby authorize and request the Commissioner of Patents and Trademarks to issue all letters patent on said invention to ASSIGNEE. ASSIGNOR(S) agree to execute all instruments and documents required for the making and prosecution of applications for United States and foreign letters patent on said invention, for litigation regarding said letters patent, or for the purpose of protecting title to said invention or letters patent therefore.

TSMC Docket No. P20191349US00
Docket No. TSMCP1091US

2019.10.25
Date

Hung-Li Chiang
Name 1st Inventor Hung-Li Chiang

TSMC Docket No. P20191349US00
Docket No. TSMCP1091US

2019/12/25
Date

Chih-Sheng Chang
Name 2nd Inventor Chih-Sheng Chang

TSMC Docket No. P20191349US00
Docket No. TSMCP1091US

2019.12.25
Date

Tzu-Chiang Chen
Name 3rd Inventor Tzu-Chiang Chen